L Number	Hits	Search Text	DB	Time stamp
1	415	257/706 and (laser or "LED" or light near	USPAT;	2004/04/30 23:15
-		emit\$3)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	481	257/433 and (laser or "LED" or light near	USPAT;	2004/04/30 23:20
		emit\$3)	US-PGPUB;	
			EPO; JPO;	
	:		DERWENT; IBM TDB	
3	301	257/707 and (laser or "LED" or light near	USPAT;	2004/04/30 23:24
	301	emit\$3)	US-PGPUB;	2001/01/30 23.21
	'		EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	253	(257/712 or 257/713 or 257/714) and (laser	USPAT;	2004/04/30 23:31
		or "LED" or light near emit\$3) same heat	US-PGPUB;	
		with (sink or slug or plate or plane or	EPO; JPO;	
		spreader or stiffener or transfer or	DERWENT;	1
_	101	dissipat43)	IBM_TDB	0004/04/20 02:21
5	101	(257/715 or 257/716 or 257/717) and (laser	USPAT;	2004/04/30 23:31
		or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or	US-PGPUB; EPO; JPO;	
		spreader or stiffener or transfer or	DERWENT;	
		dissipat43)	IBM TDB	
6	139	(257/718 or 257/719 or 257/720 or 257/721)	USPAT;	2004/04/30 23:34
*		and (laser or "LED" or light near emit\$3)	US-PGPUB;	
		same heat with (sink or slug or plate or	EPO; JPO;	
		plane or spreader or stiffener or transfer	DERWENT;	
		or dissipat43)	IBM_TDB	
7	920	(385/88 or 438/122 or 372/36) and (laser	USPAT;	2004/04/30 23:47
		or "LED" or light near emit\$3) same heat	US-PGPUB;	
		with (sink or slug or plate or plane or	EPO; JPO;	
		spreader or stiffener or transfer or dissipat43)	DERWENT; IBM TDB	
8	1052	(semiconductor or die or chip or IC) and	USPAT;	2004/04/30 23:49
ľ	1002	(laser or "LED" or light near emit\$3) same	US-PGPUB;	
		heat with (sink or slug or plate or plane	EPO; JPO;	
		or spreader or stiffener or transfer or	DERWENT;	
		dissipat43) with (double or dual or both	IBM_TDB	
		or multi\$4 or second)		
9	839		USPAT;	2004/04/30 23:50
		(laser or "LED" or light near emit\$3) same	US-PGPUB;	
		heat with (sink or slug or plate or plane or spreader or stiffener or transfer or	EPO; JPO; DERWENT;	
		dissipat43) with (double or dual or both	IBM TDB	
		or multi\$4 or second)) not ((385/88 or	15.1_155	
		438/122 or 372/36) and (laser or "LED" or		
		light near emit\$3) same heat with (sink or		
		slug or plate or plane or spreader or		
		stiffener or transfer or dissipat43))		
10	804	((semiconductor or die or chip or IC) and	USPAT;	2004/04/30 23:50
		(laser or "LED" or light near emit\$3) same	US-PGPUB;	
		heat with (sink or slug or plate or plane	EPO; JPO; DERWENT;	
		or spreader or stiffener or transfer or dissipat43) with (double or dual or both	IBM TDB	
		or multi\$4 or second)) not (((385/88 or	1511_155	
		438/122 or 372/36) and (laser or "LED" or		l i
		light near emit\$3) same heat with (sink or		
		slug or plate or plane or spreader or		
		stiffener or transfer or dissipat43)) or		
		(257/706 and (laser or "LED" or light near		
		emit\$3)) or (257/433 and (laser or "LED"		
		or light near emit\$3)) or (257/707 and		
		(laser or "LED" or light near emit\$3)) or		
		((257/712 or 257/713 or 257/714) and		
		(laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane		
		or spreader or stiffener or transfer or		
		dissipat43)))		
_	1	5454002.pn./	USPAT	2004/04/28 03:48
		/1/04 12:00:12 AM Page 1		

-	1	5454002.pn. and isolat\$3 with attach\$3	USPAT	2004/04/28 04:12
-	1	(light near emitting near device) and	USPAT	2004/04/28 04:38
		adhesive with solder with heat near sink		
_	0	(light near emitting near device) and	USPAT	2004/04/28 04:38
	ļ	adhesive with solder with heat near sink		
		with second near heat		
-	0	(light near emitting near device) and	USPAT	2004/04/28 04:38
		adhesive with heat near sink with second		
		near heat		
_	0	(light near emitting near device or laser	USPAT	2004/04/28 04:39
		or LED) and adhesive with solder with heat		
		near sink with second near heat		
-	6	(light near emitting near device or laser	USPAT ·	2004/04/28 04:43
		or LED) and adhesive with heat near sink		
		with second near heat		
-	0	(light near emitting near device or laser	USPAT	2004/04/28 04:44
		or LED) and adhesive with heat near sink		
		with heat near stiffener		
-	6	(light near emitting near device or laser	USPAT	2004/04/28 04:46
		or LED) and adhesive with heat near sink		
		with stiffener		
_	337		USPAT	2004/04/28 04:49
		or LED) and adhesive with heat near sink		
		with heat		0004 (04 (00 04 - 52
-	81		USPAT	2004/04/28 04:52
		or LED) and adhesive with heat near sink		
		with heat) and adhesive with heat near		
		sink with heat and adhesive with solder	USPAT	2004/04/28 04:52
-	3	((light near emitting near device or laser	USPAI	2004/04/20 04:32
		or LED) and adhesive with heat near sink		
		with heat) and adhesive with heat near		
		sink with heat and adhesive with solder		
		and ("AuGe" or "PbSn")		